

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jian-Hong Lin</td> <td>07/21/2005</td> </tr> <tr> <td>Kang-Cheng Lin</td> <td>07/21/2005</td> </tr> <tr> <td>Tzu-Li Lee</td> <td>07/21/2005</td> </tr> </tbody> </table>	Name	Execution Date	Jian-Hong Lin	07/21/2005	Kang-Cheng Lin	07/21/2005	Tzu-Li Lee	07/21/2005	
Name	Execution Date								
Jian-Hong Lin	07/21/2005								
Kang-Cheng Lin	07/21/2005								
Tzu-Li Lee	07/21/2005								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Co., Ltd.								
Street Address:	No. 8, Li-Hsin Road 6, Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13548039</td> </tr> </tbody> </table>	Property Type	Number	Application Number:	13548039					
Property Type	Number								
Application Number:	13548039								
CORRESPONDENCE DATA									
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ATTORNEY DOCKET NUMBER:	TSMC2004-0885 CON								
NAME OF SUBMITTER:	Jong Ho Lee								
Total Attachments: 2 source=TSMC2004_0885CON_Assignment#page1.tif source=TSMC2004_0885CON_Assignment#page2.tif									

CH \$40.00 13548039

JOINT ASSIGNMENT AND AGREEMENT

For value received, I/we, **Jian-Hong Lin, Kang-Cheng Lin and Tzu-Li Lee**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **PROTECTION LAYER FOR PREVENTING LASER DAMAGE ON SEMICONDUCTOR DEVICES** described in an application for Letters Patent of the United States filed on

July 21, 2005, 2005 and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and I/we also concurrently hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.** the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I/We authorize **Taiwan Semiconductor Manufacturing Co., Ltd.** to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me/us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I/We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of **Taiwan Semiconductor Manufacturing Co., Ltd.** to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I/We request that any and all patents for said inventions be issued to **Taiwan Semiconductor Manufacturing Co., Ltd.** in the United States and in all countries

foreign to the United States, or to such nominees as **Taiwan Semiconductor Manufacturing Co., Ltd.** may designate.

I/We agree that, when requested, I/we shall, without charge to **Taiwan Semiconductor Manufacturing Co., Ltd.** but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

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Dated: July 21, 2005

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